

Build Up HDI (Standard)	
HDI10_1+8b+1_1,50_35_engl	10 - Layers Core: 0,20 mm Cu 35/35 µm
WE-Article No.:	1 + 8B + 1
Customer:	



layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements	
Customer	WE					[µm]	[µm]	
	TOP/VS			Foil	12 µm ¹⁾		12	
						1 x 1080	60	
	2			Foil	9 µm		30	
						2 x 1080	133	
	3				35 µm		33	
				0,200 mm			200	
	4				35 µm		33	
						2 x 1080	124	
	5				35 µm		33	
			0,200 mm			200		
	6			35 µm		33		
					2 x 1080	124		
	7			35 µm		33		
			0,200 mm			200		
	8			35 µm		33		
					2 x 1080	133		
	9		Foil	9 µm		30		
					1 x 1080	60		
	BOT/RS		Foil	12 µm ¹⁾		12		

1) copper thickness outer layers: appr. 55 µm						
total material thickness:						1516
Note: Lamination thickness for Prepregs depending on layout characteristics.						

final lamination thickness:	1,52	+/-	0,12	mm			Date:	Engineer:
thickness with electro plated Cu:	1,61	+/-	0,15	mm				
total thickness with soldermask	1,67	+/-	0,17	mm				
customer requirement		+/-		mm	point:			
prepared: on 27.03.2006	by S. Keller	checked: on 04.05.2006	by M.Kress	approved: on 04.05.2006	by R.Schönholz	revision 00	page: 11+	